

Customer No.: 31561  
Docket No.: 13304-US-PA  
Application No.: 10/710,599

### REMARKS

#### Present Status of the Application

The Office Action has rejected claims 1-10 under 35 U.S.C. 102(b) as being anticipated by JP 11-087676 (JP '676), and claims 6-10 under 35 U.S.C. 102(b), as being anticipated by US 4,076,860 to Kuroda (Kuroda).

Claims 1, 4, 6 and 9 have been amended. Supporting grounds can be found at least in paragraphs [0022]-[0024]. No new matter has been added to the application by the amendments made to the claims. This Amendment is promptly filed to place the above-captioned case in condition for allowance. After carefully considering the remarks set forth in this Office Action and the cited references, Applicants respectfully submitted that the presently pending claims are in condition for allowance. Reconsideration and withdrawal of the Examiner's rejection are requested.

#### Discussions of the 102 rejections

*Claims 1-10 were rejected under 35 U.S.C. 102(b), as being anticipated by JP '676. Claims 6-10 were rejected under 35 U.S.C. 102(b), as being anticipated by US Kuroda.*

In response thereto, Applicants have amended claims 1, 4, 6 and 9, and canceled claims 2-3 and 7-8.

With respect to amended claim 1, it partly recites:

*A method of manufacturing a color filter array, comprising:*

.....

*(c) forming a second photoresist layer over the filter material layer within*

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*the openings and exposing the filter material layer over the first photoresist layer;*

*(d) removing the filter material layer over the first photoresist layer;*

*(e) removing the first photoresist layer and the second photoresist layer to form a plurality of first color filter films*

.....

**According to amended claim 1, the second photoresist layer when is formed, exposes the filter material layer over the first photoresist layer, and the filter material layer over the first photoresist layer is removed before the first and second photoresist layers are removed. Applicants submit that JP '676 fails to disclose such features for the reasons given below:**

In JP '676, as disclosed in abstract "a second resist layer 15 is formed for embedding the openings 13 to planarize a surface on the pigment layer 14" and as shown in FIG. 1(b), the second photoresist layer 15 covers the pigment layer 14 rather than exposes the pigment layer 14 as amended claim 1 recites. As much, the pigment layer 14 cannot be removed before the second photoresist layer 15 is removed since the second photoresist layer 15 covers the pigment layer 14.

Accordingly, JP '676 fails to disclose/teach all limitations of amended claim 1. Amended claim 1 should be patentable.

Claims 4 and 5 depending on allowable independent claim 1 should be patentable too.

With respect to amended claim 6, it partly recites:

*A method of manufacturing a thin film on a substrate comprising:*

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- .....
- (c) forming a second photoresist layer over the filter material layer within the openings and exposing the filter material layer over the first photoresist layer;
- (d) removing the filter material layer over the first photoresist layer;
- (e) removing the first photoresist layer and the second photoresist layer to form a plurality of first color filter films
- .....

As discussed above, JP '676 fails to disclose the features that the second photoresist layer exposes the filter material layer over the first photoresist layer, and the filter material layer over the first photoresist layer is removed before the first and second photoresist layer are removed.

Accordingly, JP '676 fails to disclose/teach all limitations of amended claim 6.

In Kuroda, *on this Al film 16, a further photoresist layer 17 is applied, as shown in FIG. 2(d)*. It is desirable for the benefit of the next succeeding step to make the surface of this photoresist layer 17 flat and smooth regardless of the irregularities in the surface of the Al film 16. (Column 2, lines 40-44) That is, the photoresist layer 17 covers the Al film 16 over the photoresistor layer 13a rather than exposes the Al film 16 over the photoresistor layer 13a as amended claim 6 recites. As such, in Kuroda, as disclosed in column 2, lines 47-52, an addition step is needed to etch the entire surface of the photoresist layer 17 for removing the surface layer of the photoresist layer 17 until the surface of the parts of the Al film 16 on the first photoresist pattern 13a are exposed, which is not needed in the instant application since the second photoresist layer when is

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formed, exposes the filter material layer over the first photoresist layer.

Therefore, Kuroda fails to disclose/teach all limitations of amended claim 6.

Accordingly, amended claim 6 should be patentable.

Claims 9-10 should be patentable too since they depend on allowable independent claim 6 directly.

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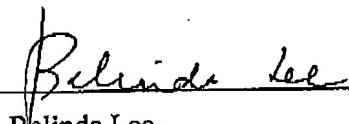
**CONCLUSION**

In view of the foregoing, it is believed that all pending claims are in proper condition for allowance. If the Examiner believes that a conference would be of value in expediting the prosecution of this application, he is cordially invited to telephone the undersigned counsel to arrange for such a conference.

Respectfully submitted,

Date :

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Belinda Lee

Registration No.: 46,863

Jianq Chyun Intellectual Property Office  
7<sup>th</sup> Floor-1, No. 100  
Roosevelt Road, Section 2  
Taipei, 100  
Taiwan  
Tel: 011-886-2-2369-2800  
Fax: 011-886-2-2369-7233  
Email: [belinda@jcipgroup.com.tw](mailto:belinda@jcipgroup.com.tw)  
[Usa@jcipgroup.com.tw](mailto:Usa@jcipgroup.com.tw)